

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY. DOCKET NO.
CLV-31563P1
APPLICATION NO.
09/911,218
APPLICANT
QIU ET AL.
FILING DATE
JULY 23, 2001

Group



U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE |
|---------------------|----|-----------------|--------|------------|-------|----------|-------------|
| <i>Jem</i> | AA | US 6, 020,175 | 2/1/00 | Onda et al | 435/ | 180 | 9/10/97 |
| | AB | | | | | | |
| | AC | | | | | | |
| | AD | | | | | | |
| | AE | | | | | | |
| | AF | | | | | | |
| | AG | | | | | | |
| | AH | | | | | | |
| | AI | | | | | | |
| | AJ | | | | | | |
| | AK | | | | | | |
| | AL | | | | | | |

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NOV 21 2003
TC 1700

FOREIGN PATENT DOCUMENTS

| | | DOCUMENT NUMBER | DATE | OFFICE | CLASS | SUBCLASS | TRANSLATION | |
|--|----|-----------------|------|--------|-------|----------|--------------------------|--------------------------|
| | | | | | | | YES | NO |
| | AM | | | | | | <input type="checkbox"/> | <input type="checkbox"/> |
| | AN | | | | | | <input type="checkbox"/> | <input type="checkbox"/> |
| | AO | | | | | | <input type="checkbox"/> | <input type="checkbox"/> |
| | AP | | | | | | <input type="checkbox"/> | <input type="checkbox"/> |
| | AQ | | | | | | <input type="checkbox"/> | <input type="checkbox"/> |

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent pages, Etc.)

| | | |
|------------|----|--|
| <i>Jem</i> | AR | Patterned Polymer Multilayer Fabrication By Controlled Adhesion Of Polyelectrolytes To Plasma-Modified Fluoropolymer Surfaces By Vargo, Calvert, Wynne, Avlyanov, MacDiarmid, & Rubner 1966. |
| <i>Jem</i> | AS | Molecular Self Assembly of Conducting Polymers: A New Layer-By-Layer Thin Film Deposition Process. By Cheung, Fou, Ferreira, & Rubner. MIT |
| | AT | |

EXAMINER

Jennifer Kolb Michener

DATE CONSIDERED

5/14/04

*EXAMINER: Initial of reference considered, whether or not citation is in conformance with MPEP 609: Draw a line through citation if not in conformance and not considered. Include a copy of this form with the next communication to applicant.